

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/10/2022

Details for "TPS3850G25QDRCRQ1"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TPS3850G25QDRCRQ1	NIPDAU	Level-2-260C-1 YEAR	TI Semiconductor	DRC 10	3x3x0.9	23.9

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.034933	97.537345	975373	0.14594	1459
Not Categorized	Proprietary Materials		0.000004	0.011169	112	0.000017	0
Precious Metals	Gold	7440-57-5	0.000018	0.050258	503	0.000075	1
Precious Metals	Palladium	7440-05-3	0.000859	2.398436	23984	0.003589	36
Precious Metals	Silver	7440-22-4	0.000001	0.002792	28	0.000004	0
Sub-Total			0.035815	100	1000000	0.149625	1496
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.29361	79.999891	799999	1.226619	12266
Thermoplastics	Epoxy	85954-11-6	0.073403	20.000109	200001	0.306657	3067
Sub-Total			0.367013	100	1000000	1.533276	15333
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	10.441595	97.585	975850	43.622028	436220
Copper and Its Alloys	Iron	7439-89-6	0.2461	2.3	23000	1.028136	10281
Copper and Its Alloys	Phosphorus	7723-14-0	0.001605	0.015	150	0.006705	67
Zinc and Its Alloys	Zinc	7440-66-6	0.0107	0.1	1000	0.044702	447
Sub-Total			10.7	100	1000000	44.701571	447016
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.243507	95.119922	951199	1.017303	10173
Precious Metals	Gold	7440-57-5	0.001997	0.780078	7801	0.008343	83
Precious Metals	Palladium	7440-05-3	0.010496	4.1	41000	0.043849	438
Sub-Total			0.256	100	1000000	1.069496	10695
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	10.064181	88.000002	880000	42.045299	420453
Other Organic Materials	Chlorine	7782-50-5	0.000114	0.000997	10	0.000476	5
Other Plastics and Rubber	Carbon Black	1333-86-4	0.03431	0.300003	3000	0.143337	1433
Thermoplastics	Epoxy	85954-11-6	1.337964	11.698998	116990	5.589635	55896
Sub-Total			11.436569	100	1000000	47.778748	47787
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	1.141122	100	1000000	4.767285	47673
Sub-Total			1.141122	100	1000000	4.767285	47673
Total			23.936519			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.

[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.